

## Usage Policy

PMGI resists uniquely suited for many critical and non-critical bi-layer lift-off processes.

### Process Guidelines

- Clean Substrate in Acetone, IPA and DI water
- Dehydration bake @200°C for 5min
- Spin coat 5ml PMGI resist between 2500 – 4500rpm achieving max uniformity (the thickness is 1.2 times greater than the metal thickness to be deposited)
- Use EBRPG to remove both edge beads and whiskers.
- Prebake at 150°C-190°C depending on film thickness.
- Coat the required e-beam resist on top of it.
- Prebake as per the e-resist requirement.
- Expose to e-beam
- Develop both resists in respective developers.
- Sputter/ evaporate the required metal
- Lastly use remover PG to lift off the bilayer stack